规格书编号

SPEC NO :

产品规格书
SPECIFICATION

CUSTOMER 客 户：

PRODUCT 产 品：SAW FILTER

MODEL NO 型 号：HDBF36A1Sa SMD-14

PREPARED 编 制： CHECKED 审 核：

APPROVED 批 准： D A T E 日 期：2006-3-21

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司

Shoulder Electronics Limited

更改历史记录
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1.SCOPE

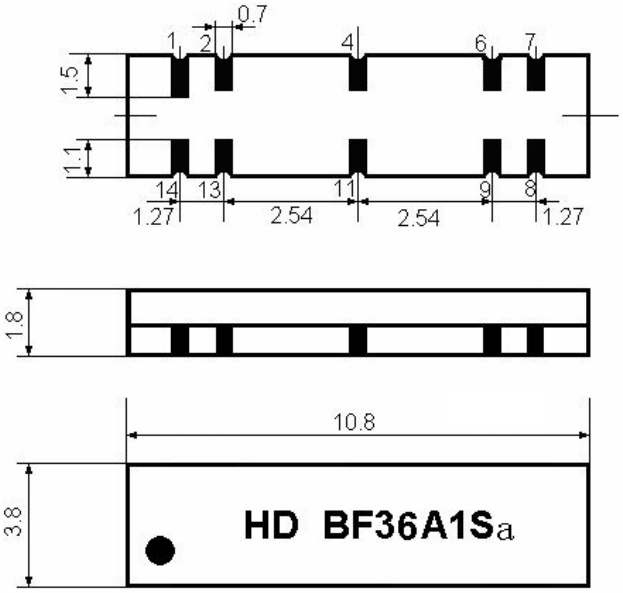
Shoulder's SAW filter series have broad line up products meeting all broadcast standard including NTSC,PAL and SECAM systems. These filters are composed of two interdigital transducers on a single-crystal. piezoelectrical chip. they are used in electronic equipments such as TV and so on.

2.Construction

2.1 Dimension and materials

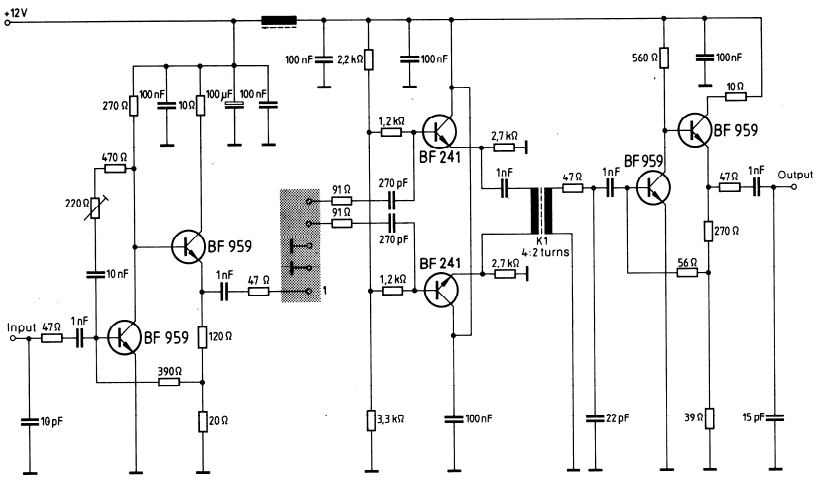
Manufacturer's name : SHOULDER ELECTRONICS LIMITED

Type : BF36A1Sa



1,14 Input
7,8 Output
2,4,6,9,11,13 ground

2.2. Circuit construction, measurement circuit



Test circuit for SIP-5 filter
Input impedance of the symmetrical post-amplifier: 2 kΩ in parallel with 3 pF

3.Characteristics

Items	Conditions	Specifications
Standard atmospheric conditions	Unless otherwise specified , the standard rang of atmospheric conditions for making measurements and tests is as follows; Ambient temperature : 15℃ to 35℃ Relative humidity : 25% to 85% Air pressure : 86kPa to 106kPa	There shall be no damage.
Operating temperature rang	Operating temperature rang is the rang of ambient temperatures in which the filter can be operated continuously. -20℃ ~ +60℃	
Storage temperature rang	Storage temperature rang is the rang of ambient temperatures at which the filter can be stored without damage. Conditions are as specified elsewhere in these specifications. -40℃ ~ +70℃	
Reference temperature	+25℃	

3.1 Maximum Rating

DC voltage	**VDC**	**12**	**V**	**Between any terminals**
AC voltage	**Vpp**	**10**	**V**	**Between any terminals**

3.2 Electrical Characteristics

Source impedance Zs=50Ω

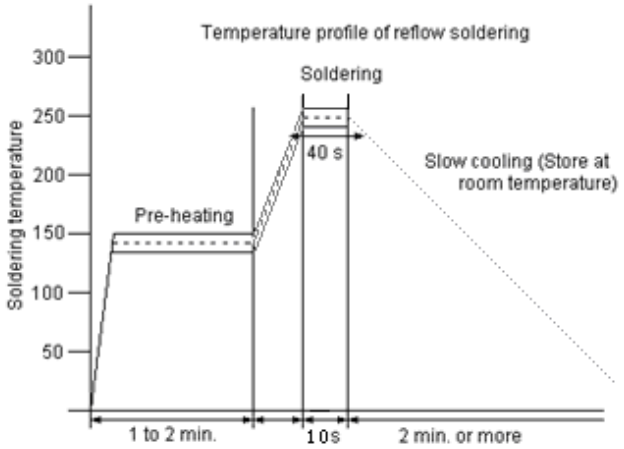
Load impedance Z_L=2kΩ//3pF T_A=25℃

Item	Freq	min	typ	max	
Center frequency	Fo	-	36.125	-	MHz
Insertion attenuation Reference level	36.125MHz	18.3	20.3	22.3	dB
Amplitude ripple: 32.65~39.60 MHz		0.0	0.6	1.2	dB
Pass bandwidth	B3dB	-	8.0	-	MHz
	B30dB	-	9.4	-	MHz
Relative attenuation	32.32MHz	-0.6	0.9	2.4	dB
	39.93MHz	-0.1	1.4	2.9	dB
	32.13MHz	0.9	2.7	4.5	dB
	31.25MHz	28.0	38.0	-	dB

	47.25MHz	35.0	45.0	-	dB
Sidelobe	25.00~31.25MHz	30.0	40		dB
	40.90~50.00MHz	30.0	38		dB
Temperature coefficient		-72			ppm/k

3.3Environmental Performance Characteristics

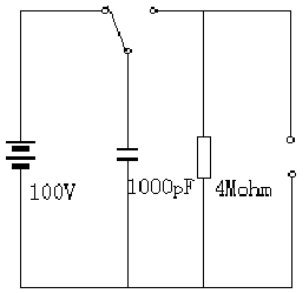
<table>
<tr><th>Item</th><th>Condition</th><th>Specifications</th></tr>
<tr><td>High temperature</td><td>The specimen shall be store at a temperature of 80±2℃ for 96±4h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurement shall be made within 1h.</td><td rowspan="5">Mechanical characteristics and specifications in electrical characteristics shall be satisfied. There shall be no excessive change in appearance.</td></tr>
<tr><td>Low temperature</td><td>The specimen shall be store at a temperature of -20±3℃ for 96±4h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurement shall be made within 1h.</td></tr>
<tr><td>Humidity</td><td>The specimen shall be store at a temperature of 40±2℃ with relative humidity of 90% to 96% for 96±4h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurement shall be made within 1h.</td></tr>
<tr><td>Thermal shock</td><td>The specimen shall be subjected to 8 continuous cycles each as shown below. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurement shall be made within 1h.
<table>
<tr><th></th><th>Temperature</th><th>Duration</th></tr>
<tr><td>1</td><td>+25℃=>-40℃</td><td>0.5h</td></tr>
<tr><td>2</td><td>-40℃</td><td>4h</td></tr>
<tr><td>3</td><td>-40℃=>+85℃</td><td>2h</td></tr>
<tr><td>4</td><td>+85℃</td><td>4h</td></tr>
<tr><td>5</td><td>+85℃=>+25℃</td><td>0.5h</td></tr>
<tr><td>6</td><td>+25℃</td><td>1h</td></tr>
</table></td></tr>
<tr><td>Resistance to Soldering heat</td><td>Reflow soldering method
Peak: 255 ±5 ℃, 220 ±5℃, 40s
At electrode temperature of the specimen.</td></tr>
</table>

	 The specimen shall be passed through the reflow furnace with the condition shown in the above profile for 1 time. The specimen shall be stored at standard atmospheric conditions for 1h, after which the measurement shall be made. Test board shall be 1.6 mm thick. Base material shall be glass fabric base epoxy resin.	
Solder ability	Immerse the pins melt solder at 260℃+5/-0℃ for 5 sec.	More then 95% of total area of the pins should be covered with solder

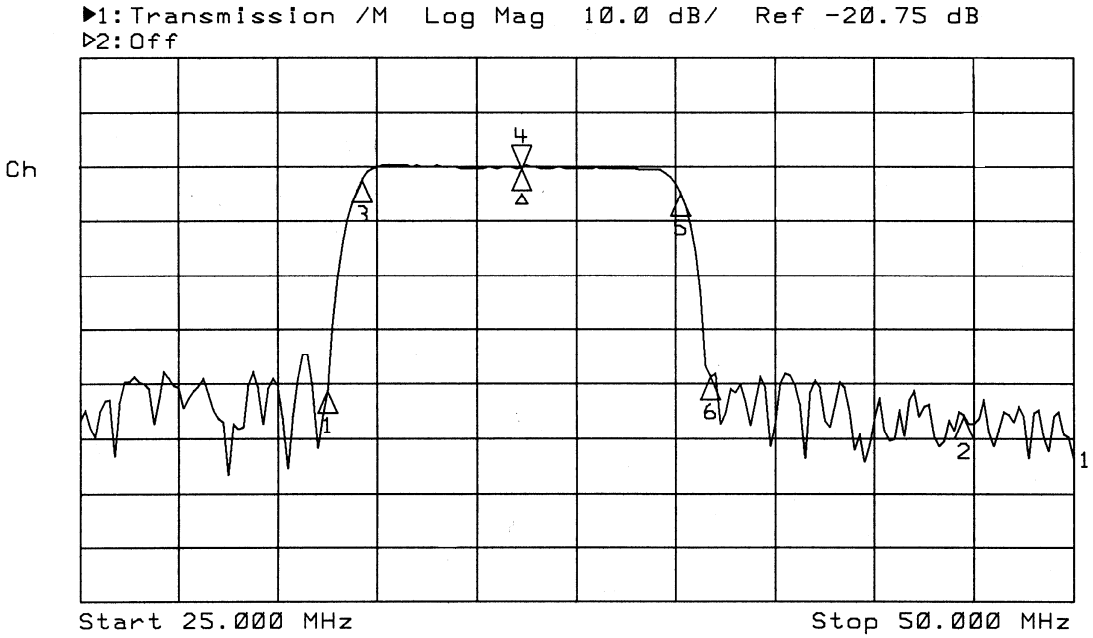
3.4Mechanical Test

Items	Conditions	Specifications
Vibration	600-3300rpm amplitude 1.5mm 3 directions 2 H each	There shall be no damage.
Drop	On maple plate from 1m high 3 times	
Lead pull	Pull with 1kg force for 30 seconds	
Lead bend	90^{o} bending with 500g weigh 2 times	

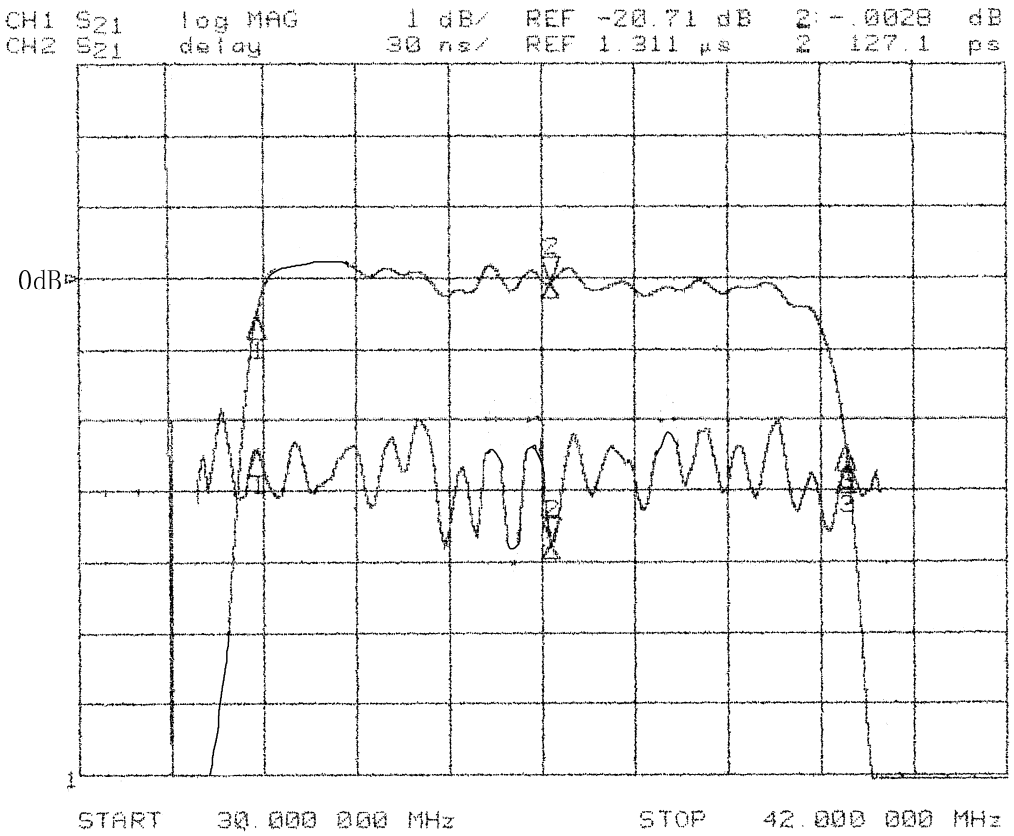
3.5Voltage Discharge Test

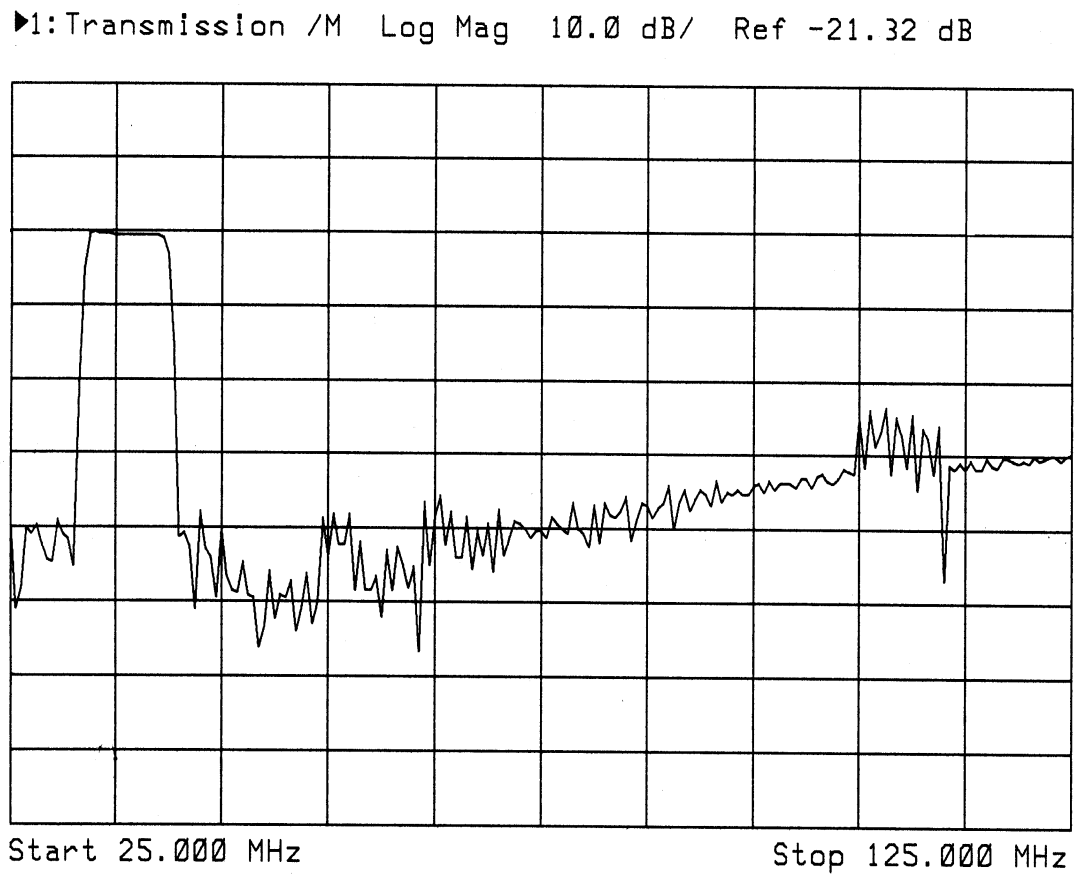
Item	Condition	Specifications
Surge	Between any two electrode 	There shall be no damage

3.6 Frequency response



Mkr	ΔFreq (MHz)	Ch 1 (dB)	Freq (MHz)	Ch 2 (dB)
1	-4.875	-41.12		
2	11.125	-45.78		
3	-3.995	-2.10		
4	0.000	0.00		
5	4.005	-4.82		
6	4.775	-38.51		
7				
8				


CH1 S21 log MAG 1 dB/ REF -20.71 dB 2: -.0028 dB
CH2 S21 delay 30 ns/ REF 1.311 µs 2 127.1 ps
0dB
START 30.000 000 MHz
STOP 42.000 000 MHz



4. REMARK

4.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

4.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

4.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

5. Packing

5.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

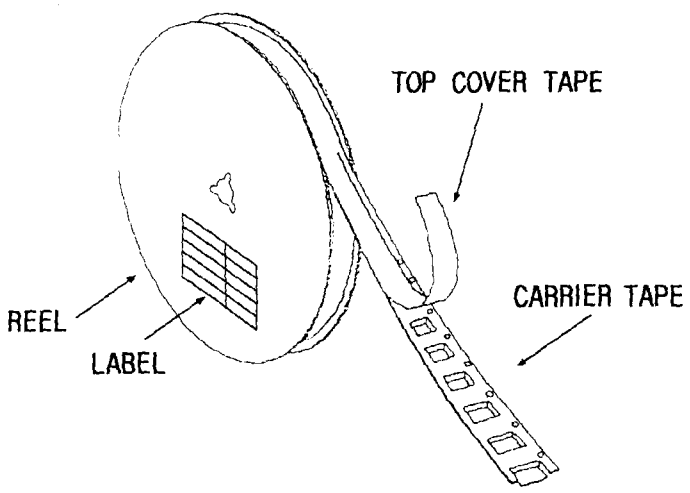
5.2 Reeling Quantity

1000 pcs/reel 7”

3000 pcs/reel 13”

5.3 Taping Structure

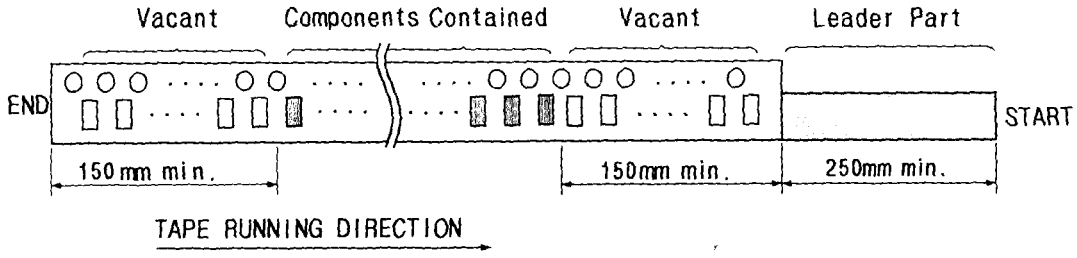
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



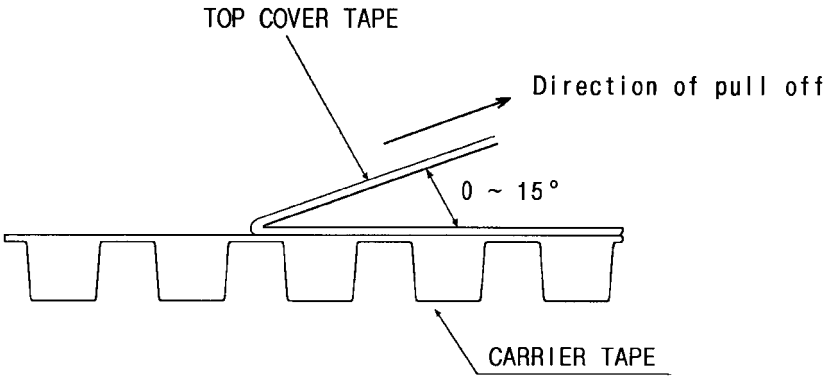
6. TAPE SPECIFICATIONS

6.1 Tensile Strength of Carrier Tape: 4.4N/mm width

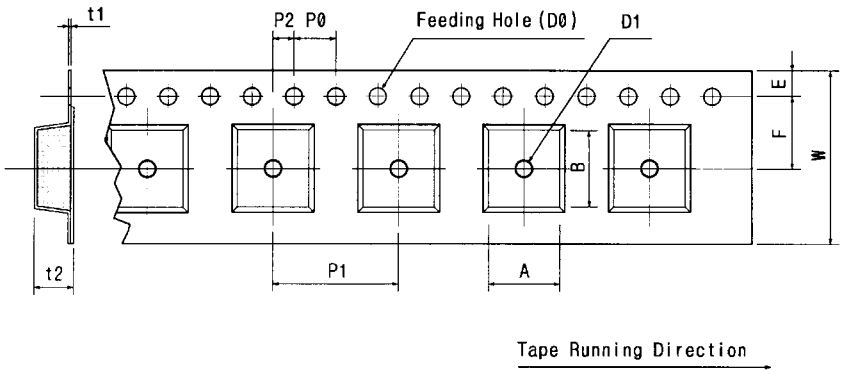
6.2 Top Cover Tape Adhesion (See the below figure)

(1) pull off angle: 0~15°

(2) speed: 300mm/min.
(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

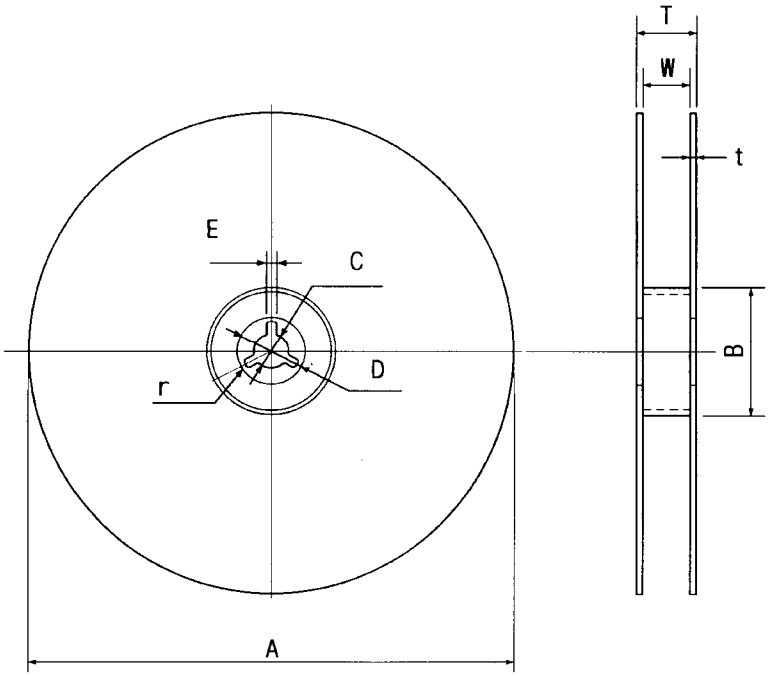


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
24.00 ±0.3	11.50 ±0.10	1.75 ±0.1	4.0 ±0.1	8.0 ±0.1	2.0 ±0.10	Ø1.50	Ø1.50 MIN	0.3 ±0.05	2.10 ±0.1	6.40 ±0.1	11.10 ±0.1

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
Ø330 ±1.0	Ø100 ±0.5	Ø13 ±0.5	Ø21 ±0.8	2 ±0.5	12.40 ±0.20	3 max.	1.0 max.